



1733/DM

PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

June 19, 2007

Applicants: Eiji HINO et al

For: ELECTROLESS GOLD PLATING LIQUID

Serial No.: 10/549 537 Group: 1755

Confirmation No.: 1357

Filed: September 15, 2005 Examiner: Klemanski

International Application No.: PCT/JP2005/005936

International Filing Date: March 29, 2005

Atty. Docket No.: 4700.P0317US

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE**

Sir:

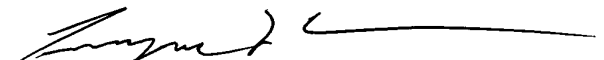
In response to the Office Action dated April 3, 2007,  
please amend the above-identified application as follows:

(Please see following pages.)

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**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being  
deposited with the United States Postal Service with  
sufficient postage as first class mail in an envelope  
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Alexandria, VA 22313-1450, on June 19, 2007.

  
Terryence F. Chapman